

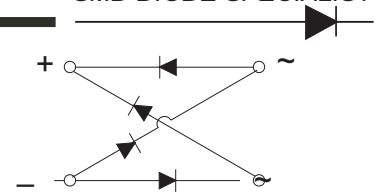
Schottky Bridge Rectifiers

COMCHIP
SMD DIODE SPECIALIST

CDBHD280-G Thru 2100-G

Reverse Voltage: 80 - 100 Volts

Forward Current: 2.0 Amp



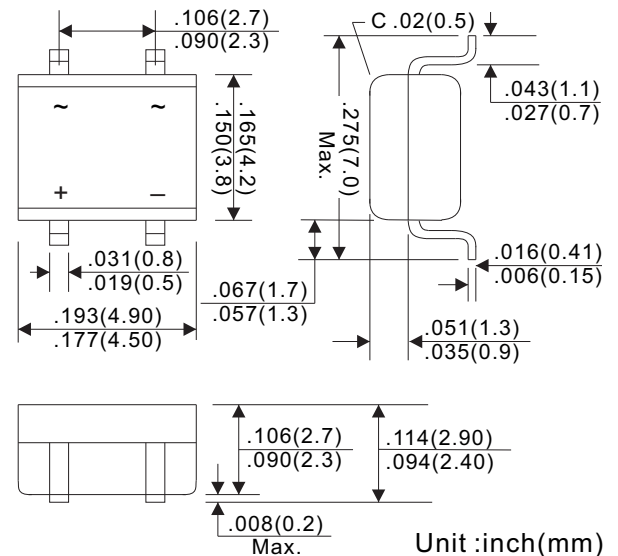
Features

- Schottky barrier chips in bridge
- Metal-Semiconductor junction with guard ring
- Highsurge current capability
- Silicon epitaxial planar chips
- For use in low voltage, high efficiency inverters, free wheeling, and polarity protection applications
- Lead-free part, meet RoHS requirements

Mechanical Data

- Case: Mini-Dip bridge (TO-269AA) plastic molded case
- Epoxy: UL94-V0 rated flame retardant
- Terminals: Solderable per MIL-STD-750 Method 2026
- Polarity: As marked on body
- Mounting Position: Any
- Weight: 0.0078 ounces, 0.22 grams

Mini-DIP



MAXIMUM RATING AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified

<i>CDBHD</i> - Symbols	280	290	2100	Units	
Maximum Recurrent Peak Reverse Voltage	VRRM	80	90	100	Volts
Maximum RMS Voltage	VRMS	56	63	70	Volts
Maximum DC Blocking Voltage	VDC	80	90	100	Volts
Maximum Average Forward Rectified Current 0.2x0.2" (5.0x5.0mm) copper pad area, see Figure 1	I _{AV}	2.0		Amps	
Peak Forward Surge Current 8.3mS single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	50.0		Amps	
Maximum Forward Voltage at 1.0A (Note 1)	V _F	0.85		Volts	
Maximum DC Reverse Current at Rated DC Blocking Voltage	I _R	0.5 20.0		mA	
Typical Junction Capacitance (Note 2)	C _J	125		pF	
Typical Thermal Resistance (Note 3)	R _{θJA} R _{θJL}	85.0 20.0		°C/W	
Operating Junction Temperature Range	T _J	-55 ~ +125		°C	
Storage Temperature Range	T _{STG}	-55 ~ +150		°C	

Note 1. Pulse test: 300µS pulse width, 1% duty cycle

2. Measured at 1.0MHz and applied reverse voltage of 4.0 Volts

3. Thermal resistance from junction to ambient and from junction to lead P.C.B. mounted on 0.2x0.2"(5.0x5.0mm) copper pad areas.

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Fig. 1 - Forward Current Derating Curve

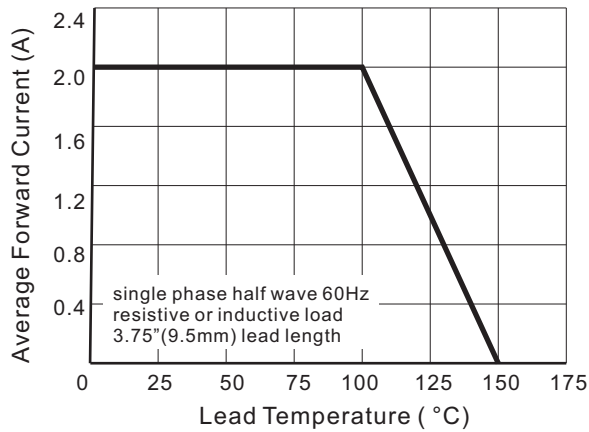


Fig. 2 - Maximum Non-Repetitive Peak Forward Surge Current

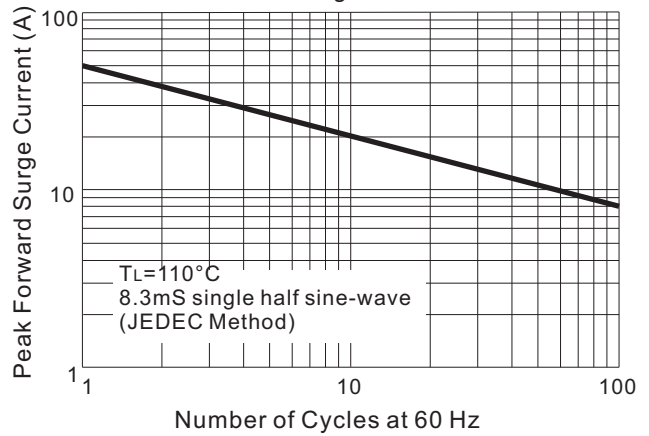


Fig. 3 - Typical Instantaneous Forward Characteristics

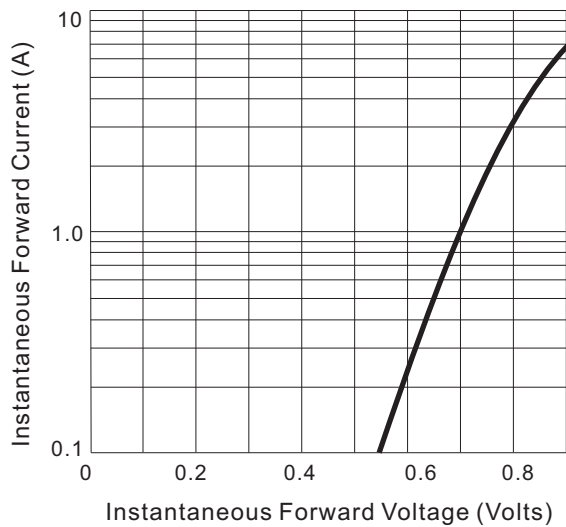


Fig. 4 - Typical Reverse Characteristic

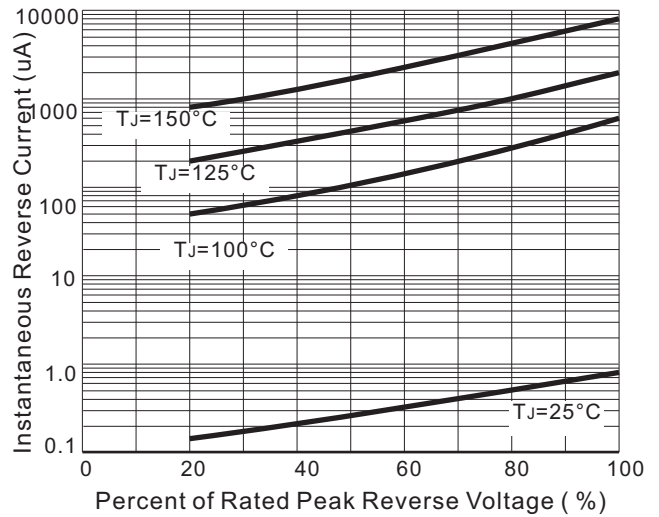


Fig. 5 - Typical Junction Capacitance

